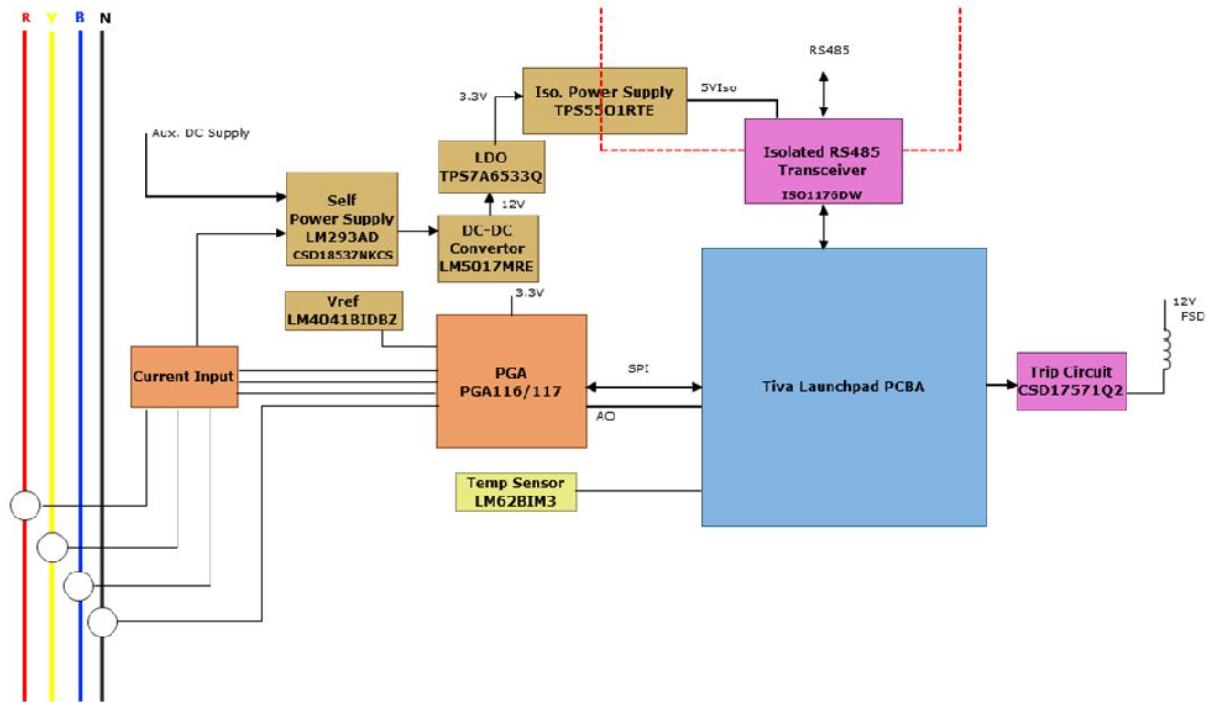


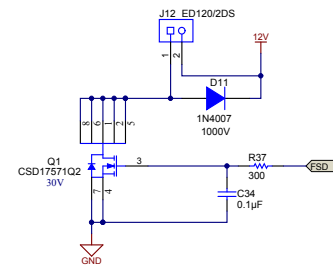
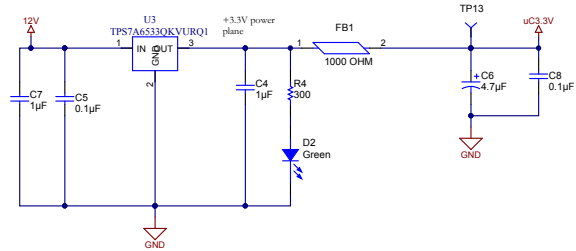
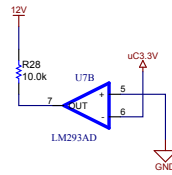
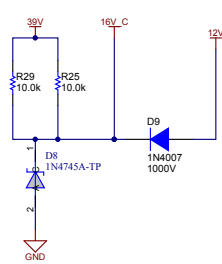
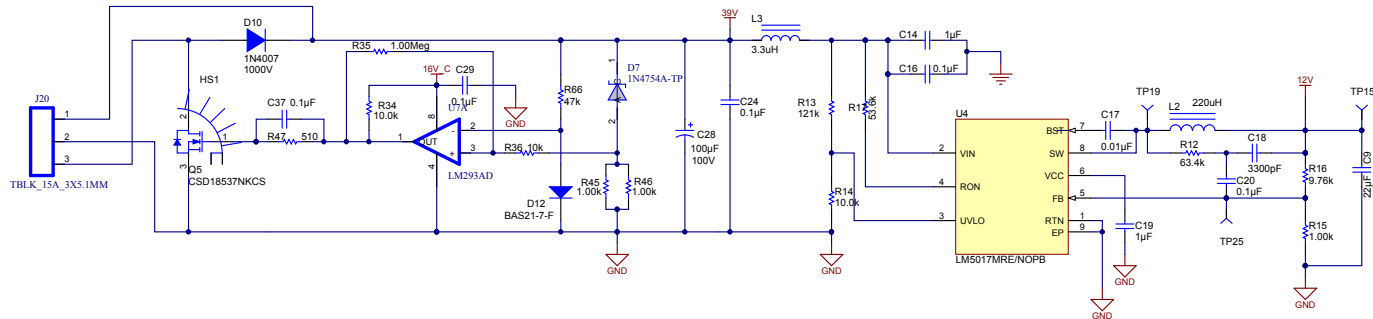
Page 2	BLOCK DIAGRAM
Page 3	SELF POWER + REGULATOR +FSD +LDO
Page 4	ANALOG FRONT END PGA +REF+TEMP SENSOR
Page 5	ISOLATED RS485 INTERFACE
Page 6	LAUNCH PAD INTERFACE
Page 7	HARDWARE - MISCELLANEOUS

Revision History	
Revision	Notes



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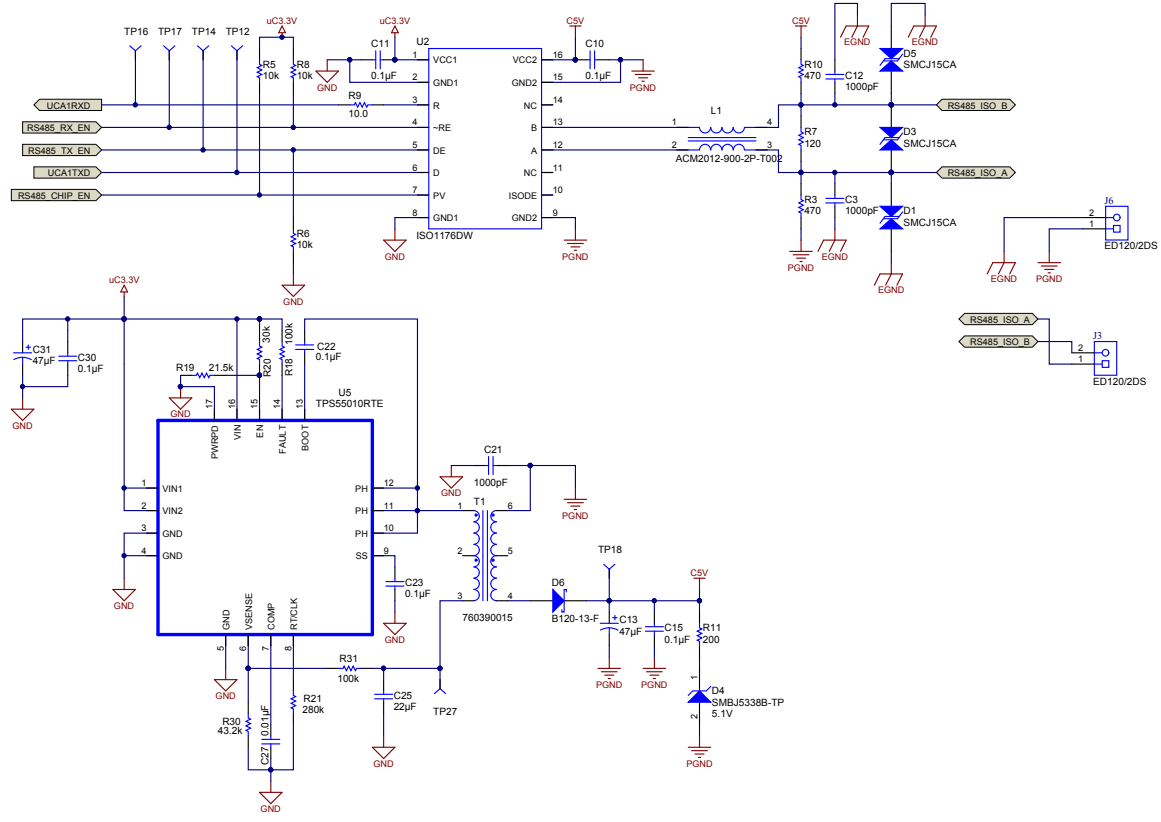
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SVN Rev.: Not in version control	Assembly Variant: 001	Project Title: TIDA-00130 PGA BASED MCCB-ETU	Sheet Title:
Drawn By:	File: Pcd Block Diagram.SchDoc	Sheet: 2 of 7	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	http://www.ti.com	



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Designed for: Public Release | Mod. Date: 2/13/2014
 Project Title: TIDA-00130 PGA BASED MCCB-ETU
 Number: TIDA-00130 | Rev: E2
 SVN Rev.: Not in version control | Assembly Variant: 001 | Sheet: 3 of 7
 Drawn By: | File: Pcb-Scp.Doc | Size: B
 Engineer: Enter name of project lead | Contact: http://www.ti.com/support





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Number: TIDA-00130	Rev: E2	Designed for: Public Release	Mod. Date: 1/31/2014
SVN Rev.: Not in version control	Assembly Variant: 001	Project Title: TIDA-00130 PGA BASED MCCB-ETU	
Drawn By:	Engineer: Enter name of project lead	File: Pa5-Sc3Doc	Sheet: 5 of 7
	Contact: http://www.ti.com/support		Size: B



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A

A

B

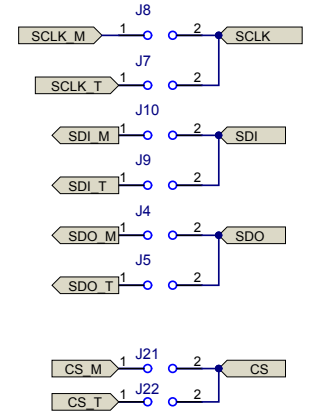
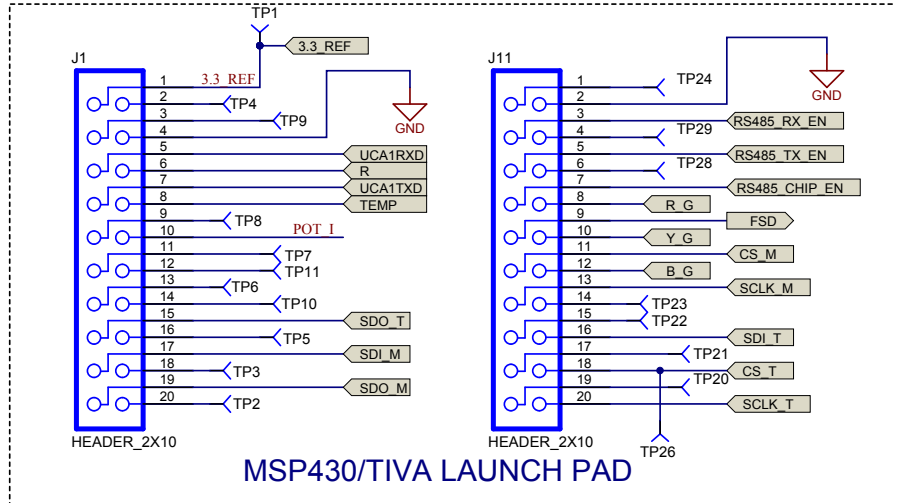
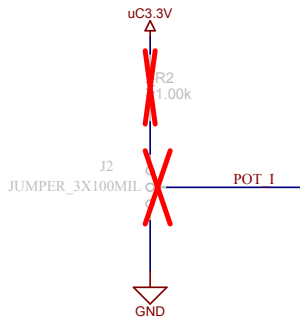
B

C

C

D

D



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Number: TIDA-00130 | Rev: E2
SVN Rev: Not in version control
Drawn By:
Engineer: Enter name of project lead

Designed for: Public Release | Mod. Date: 2/21/2014
Project Title: TIDA-00130 PGA BASED MCCB-ETU
Sheet Title:
Assembly Variant: 001 | Sheet: 6 of 7
File: Pg6_SchDoc | Size: A4
Contact: <http://www.ti.com/support>



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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H6 1902C H5 1902C H9 1902C H8 1902C

QF
MH 3.2MM

FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: TIDA-00130
PCB Rev: E2

PCB
LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

Z21
Label Assembly Note
This Assembly Note is for PCB labels only

Z22
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: TIDA-00130	Rev: E2	Designed for: Public Release	Mod. Date: 1/31/2014
SUN Rev.: Not in version control		Project Title: TIDA-00130 PGA BASED MCCB-ETU	
Drawn By:	Engineer: Enter name of project lead	Assembly Variant: 001	Sheet: 7 of 7
File: P07_Hardware.SchDoc		Size: B	
Contact: http://www.ti.com/support			



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